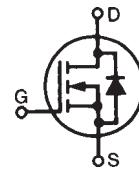


# High Voltage Power MOSFET

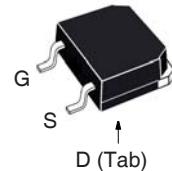
## IXTT12N150HV

**V<sub>DSS</sub>** = 1500V  
**I<sub>D25</sub>** = 12A  
**R<sub>DS(on)</sub>** ≤ 2.2Ω



N-Channel Enhancement Mode  
Fast Intrinsic Diode

TO-268HV



G = Gate      D = Drain  
 S = Source      Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V <sub>DSS</sub>	T <sub>J</sub> = 25°C to 150°C	1500	V
V <sub>DGR</sub>	T <sub>J</sub> = 25°C to 150°C, R <sub>GS</sub> = 1MΩ	1500	V
V <sub>GSS</sub>	Continuous	±30	V
V <sub>GSM</sub>	Transient	±40	V
I <sub>D25</sub>	T <sub>C</sub> = 25°C	12	A
I <sub>DM</sub>	T <sub>C</sub> = 25°C, Pulse Width Limited by T <sub>JM</sub>	40	A
I <sub>A</sub>	T <sub>C</sub> = 25°C	6	A
E <sub>AS</sub>	T <sub>C</sub> = 25°C	750	mJ
dv/dt	I <sub>S</sub> ≤ I <sub>DM</sub> , V <sub>DD</sub> ≤ V <sub>DSS</sub> , T <sub>J</sub> ≤ 150°C	5	V/ns
P <sub>D</sub>	T <sub>C</sub> = 25°C	890	W
T <sub>J</sub>		- 55 ... +150	°C
T <sub>JM</sub>		150	°C
T <sub>stg</sub>		- 55 ... +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering	300	°C
T <sub>sold</sub>	Plastic Body for 10s	260	°C
Weight		4	g

### Features

- High Blocking Voltage
- High Voltage Package
- Fast Intrinsic Diode
- Low Package Inductance

### Advantages

- Easy to Mount
- Space Savings
- High Power Density

Symbol	Test Conditions (T <sub>J</sub> = 25°C, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	1500		V
V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2.5		V
I <sub>GSS</sub>	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V			±100 nA
I <sub>DSS</sub>	V <sub>DS</sub> = V <sub>DSS</sub> , V <sub>GS</sub> = 0V T <sub>J</sub> = 125°C			25 μA 500 μA
R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.5 • I <sub>D25</sub> , Note 1			2.2 Ω

### Applications

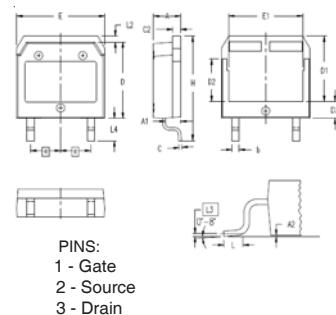
- High Voltage Power Supplies
- Capacitor Discharge
- Pulse Circuits

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$V_{DS} = 20\text{V}$ , $I_D = 0.5 \cdot I_{D25}$ , Note 1	8	13	S
$C_{iss}$ $C_{oss}$ $C_{rss}$	$V_{GS} = 0\text{V}$ , $V_{DS} = 25\text{V}$ , $f = 1\text{MHz}$	3720		pF
		240		pF
		80		pF
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	<b>Resistive Switching Times</b> $V_{GS} = 10\text{V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 0.5 \cdot I_{D25}$ $R_G = 2\Omega$ (External)	26		ns
		16		ns
		53		ns
		14		ns
$Q_{g(on)}$ $Q_{gs}$ $Q_{gd}$	$V_{GS} = 10\text{V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 0.5 \cdot I_{D25}$	106		nc
		17		nc
		50		nc
$R_{thJC}$			0.14	°C/W

### Source-Drain Diode

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$I_s$	$V_{GS} = 0\text{V}$		12	A
$I_{SM}$	Repetitive, Pulse Width Limited by $T_{JM}$		48	A
$V_{SD}$	$I_F = I_S$ , $V_{GS} = 0\text{V}$ , Note 1		1.4	V
$t_{rr}$ $I_{RM}$ $Q_{RM}$	$I_F = 6\text{A}$ , $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$ , $V_{GS} = 0\text{V}$	1.2		μs
		24.5		A
		14.8		μC

### TO-268HV Outline

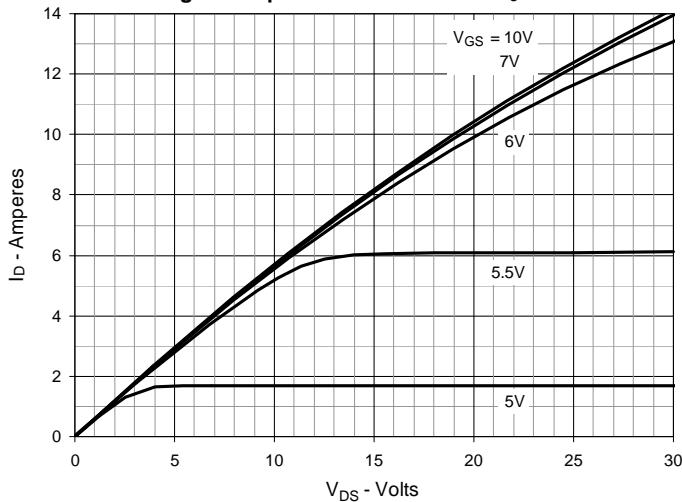
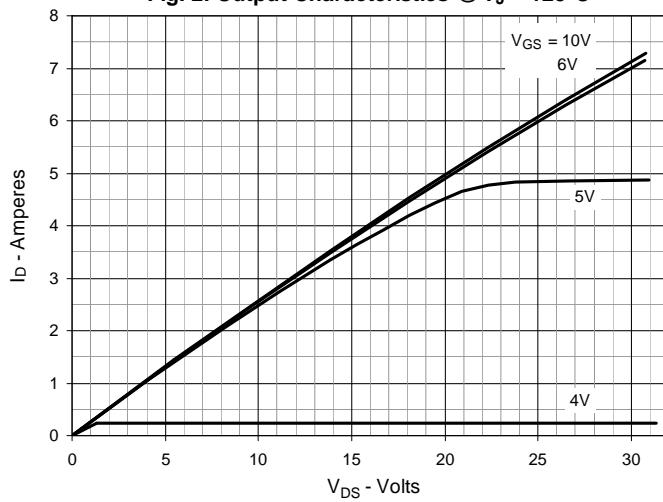
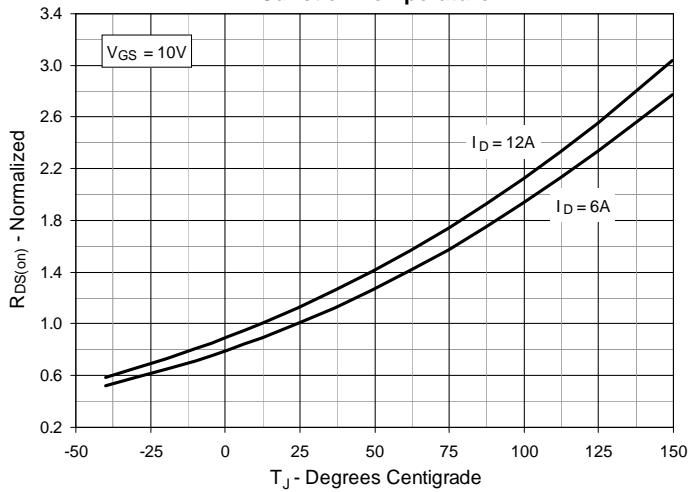
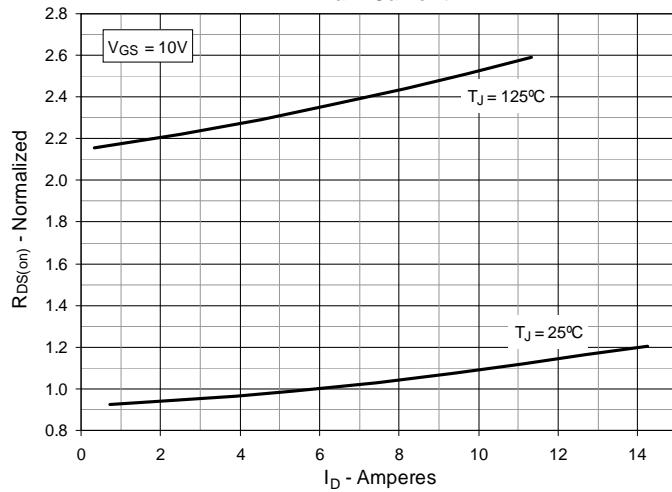
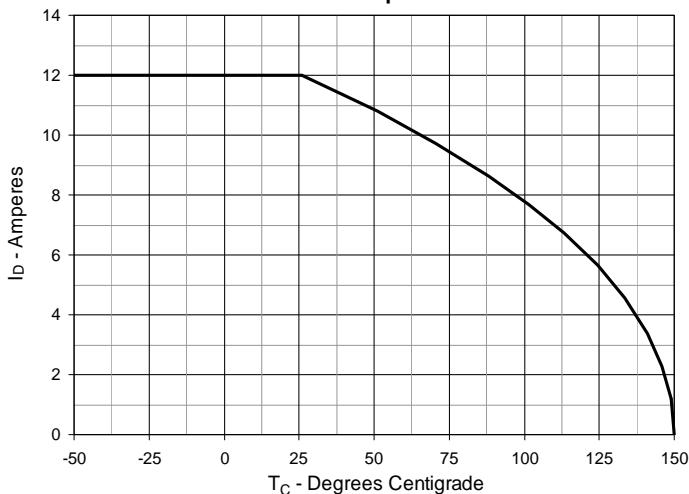
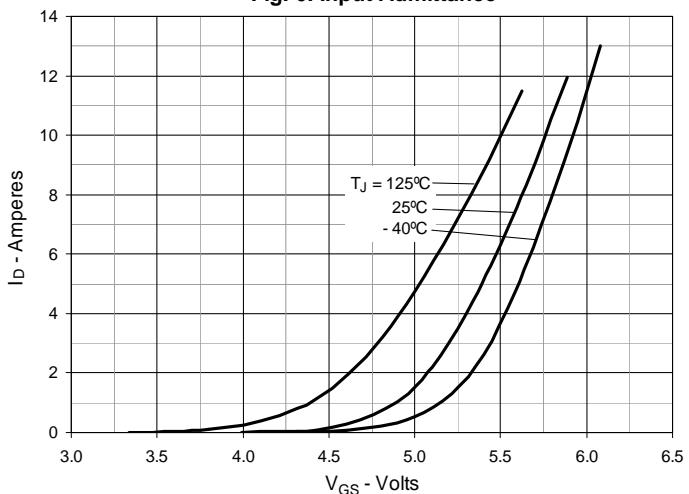


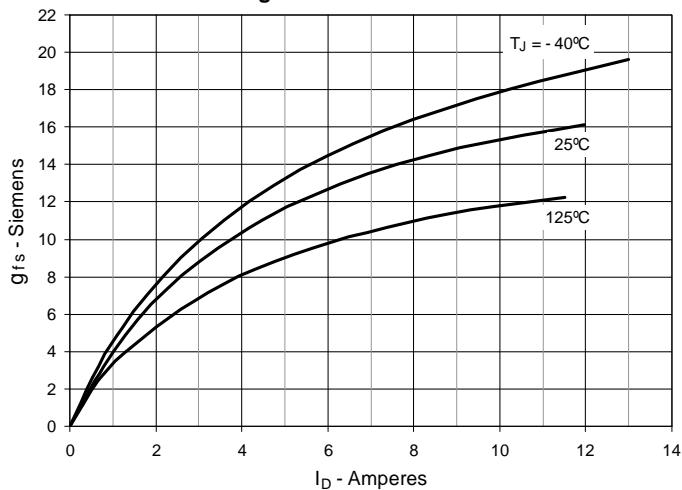
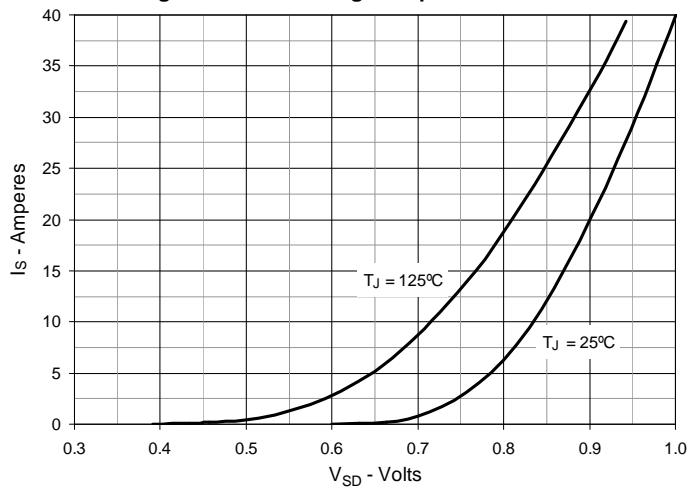
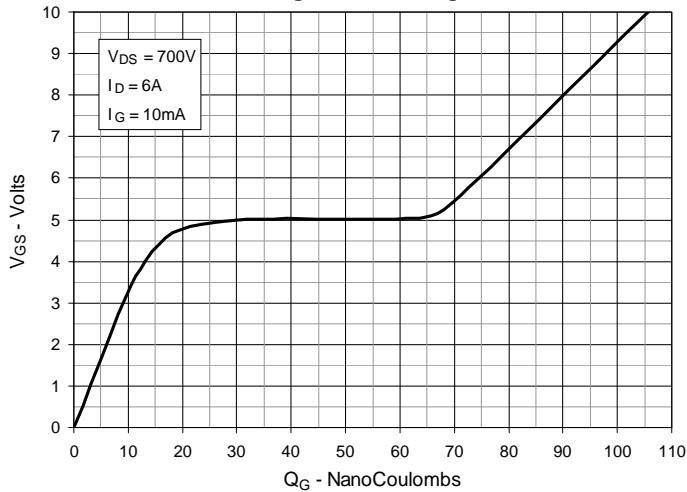
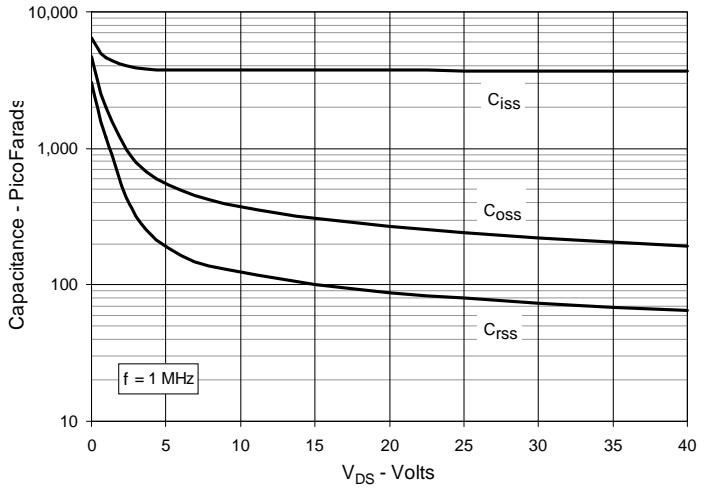
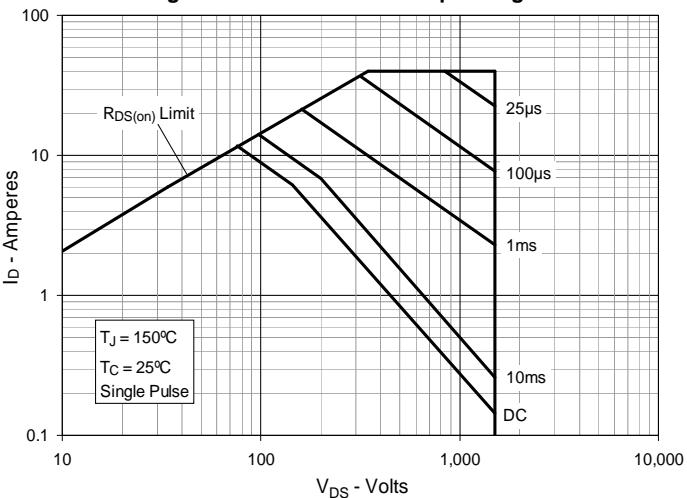
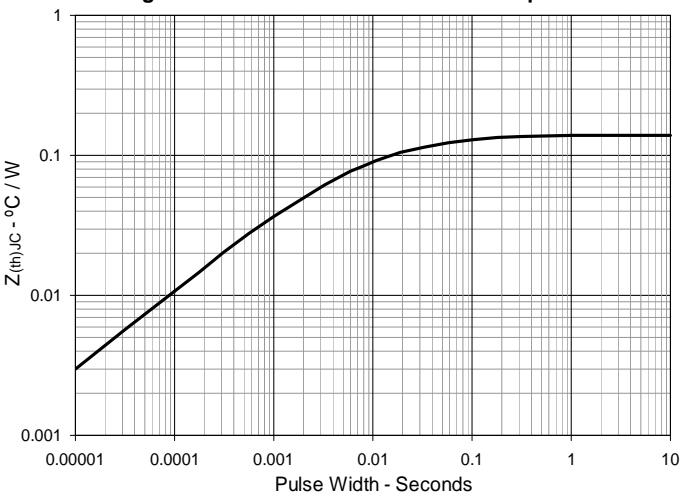
Dim.	Millimeter		Inches	
	min	max	min	max
A	4.90	5.10	0.193	0.201
A1	2.70	2.90	0.106	0.114
A2	0.02	0.25	0.001	0.100
b	1.15	1.45	0.045	0.057
C	0.40	0.65	0.016	0.026
C2	1.45	1.60	0.057	0.063
D	13.80	14.00	0.543	0.551
D1	11.80	12.10	0.465	0.476
D2	7.50	7.80	0.295	0.307
D3	2.90	3.20	0.114	0.126
E	15.85	16.05	0.624	0.632
E1	13.30	13.60	0.524	0.535
e	5.45	BSC	0.215	BSC
H	18.70	19.10	0.736	0.752
L	1.70	2.00	0.067	0.079
L2	1.00	1.15	0.039	0.045
L3	0.25	BSC	0.010	BSC
L4	3.80	4.10	0.150	0.161

Note 1. Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .

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**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$** **Fig. 2. Output Characteristics @  $T_J = 125^\circ\text{C}$** **Fig. 3.  $R_{DS(on)}$  Normalized to  $I_D = 6\text{A}$  Value vs. Junction Temperature****Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = 6\text{A}$  Value vs. Drain Current****Fig. 5. Maximum Drain Current vs. Case Temperature****Fig. 6. Input Admittance**

**Fig. 7. Transconductance****Fig. 8. Forward Voltage Drop of Intrinsic Diode****Fig. 9. Gate Charge****Fig. 10. Capacitance****Fig. 11. Forward-Bias Safe Operating Area****Fig. 12. Maximum Transient Thermal Impedance**

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